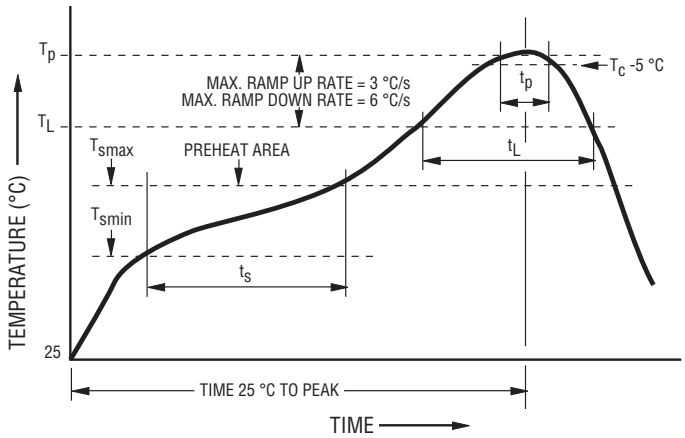
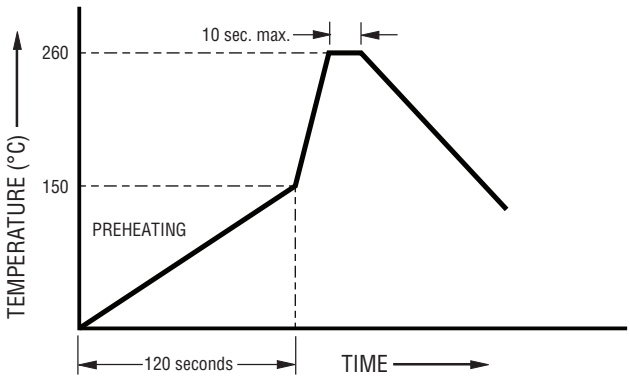
## Solder Reflow Recommendations




| Profile Feature | Pb-Free Assembly |
|---|---|
| Preheat / Soak:<br>Temperature Min. ($T_{smin}$)<br>Temperature Max. ($T_{smax}$)<br>Time ($t_s$) from ($T_{smin}$ to $T_{smax}$) | <br>150 °C<br>200 °C<br>60~120 seconds |
| Ramp Up Rate ($T_L$ to $T_p$) | 3 °C / second max. |
| Liquidous Temperature ($T_L$)<br>Time ($t_L$) maintained above $T_L$ | 217 °C<br>60~150 seconds |
| Peak Package Body Temperature ($T_p$) | 260 °C |
| Time ($t_p$)* within 5 °C of the specified classification temperature ($T_c$) | 30 seconds* |
| Ramp Down Rate ($T_p$ to $T_L$) | 6 °C / second max. |
| Time 25 °C to Peak Temperature | 8 minutes max. |

* Tolerance for peak profile temperature (Tp ) is defined as a supplier minimum and a user maximum.

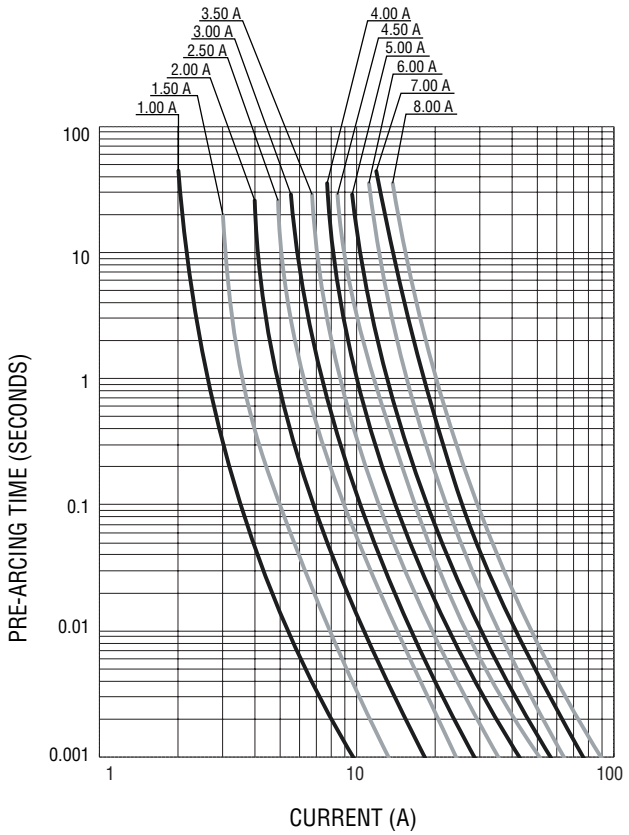
## Recommended Temperature Profile for Wave Soldering



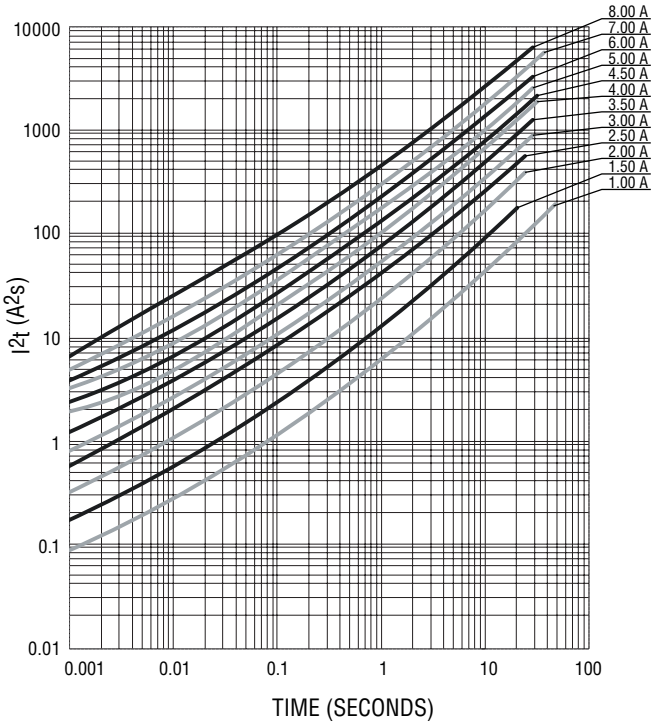

Wave soldering is suitable for 0603 size models.

Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.

## Average Pre-Arcing Time vs. Current Curves




## Average $I^2t$ vs. t Curves



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